

AMPLIFY™ EA 101

Functional Polymer

陶氏塑料

产品说明

AMPLIFY™ EA 101 Functional Polymer is produced via a high-pressure reactor. This ethylene-ethyl acrylate (EEA) copolymer exhibits high flexibility and imparts low temperature toughness to a wide range of engineering resins. This polymer demonstrates excellent blend compatibility with other polyolefins. It can be utilized as a tie layer between polyolefins and a variety of polar substrates, such as metal, polyvinylidene chloride (PVDC), polyolefins, cellulose, polyester, polycarbonate, glass, foil, PVC, PET, and Polystyrene.

High performance packaging applications
Polymer modification
Tie layer to PVDC and Polyolefins
Superior additive concentrate carrier
Low gels with excellent thermal stability
Complies with:
U.S. FDA 21 CFR 175.105
U.S. FDA 21 CFR 177.1320 (with Restrictions)
EU, No 10/2011
Consult the regulations for complete details.

| 基本信息 | | | | |
|-----------------------------|---|---------------------|----------------------|--|
| 机构评级 | FDA 21 CFR 175.105 | FDA 21 CFR 177.1320 | 欧洲 No 10/2011 | |
| 形式 | 粒子 | | | |
| 加工方法 | 吹塑成型 | 挤出涂层 | | |
| 物理性能 | 额定值 | 单位制 | 测试方法 | |
| 比重 | 0.931 | g/cm³ | ASTM D792, ISO 1183 | |
| 熔流率(熔体流动速率) (190°C/2.16 kg) | 6.0 | g/10 min | ASTM D1238, ISO 1133 | |
| 共聚单体含量 ¹ | 18.5 | % | ASTM D3594 | |
| 硬度 | 额定值 | 单位制 | 测试方法 | |
| 肖氏硬度 | | | ASTM D2240, ISO 868 | |
| 邵氏 A | 86 | | ASTM D2240, ISO 868 | |
| 邵氏 D | 31 | | ASTM D2240, ISO 868 | |
| 机械性能 | 额定值 | 单位制 | 测试方法 | |
| 抗张强度 | | | ASTM D638, ISO 527-2 | |
| 屈服 | 2.96 | MPa | ASTM D638, ISO 527-2 | |
| 断裂 | 13.4 | MPa | ASTM D638, ISO 527-2 | |
| 伸长率 | | | ASTM D638, ISO 527-2 | |
| 屈服 | 10 | % | ASTM D638, ISO 527-2 | |
| 断裂 | 750 | % | ASTM D638, ISO 527-2 | |
| 弯曲模量 - 2% 正割 | 55.2 | MPa | ASTM D790B, ISO 178 | |
| 冲击性能 | 额定值 | 单位制 | 测试方法 | |
| 拉伸冲击强度 ² | 672 | kJ/m² | ASTM D1822 | |
| 热性能 | 额定值 | 单位制 | 测试方法 | |
| 载荷下热变形温度 (0.45 MPa, 未退火) | 31.1 | °C | ASTM D648 | |
| 脆化温度 | < -76.1 | °C | ASTM D746 | |
| 维卡软化温度 | 57.2 | °C | ASTM D1525, ISO 306 | |
| 熔融温度(DSC) | 97.8 | °C | 内部方法 | |
| 结晶峰温度 (DSC) | 82.8 | °C | 内部方法 | |
| 补充信息 | | | | |
| 根据 ASTM D 4976 进行模塑和测试. | | | | |
| 备注 | | | | |
| 1. | 校准范围为 15 - 20% EA;路径长度已标准化;基板/薄膜厚度为 15 密尔;压机温度为 160°C | | | |
| 2. | 类型 S | | | |